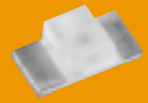




Product Guide

1111R Series Reverse Mount SMT LED



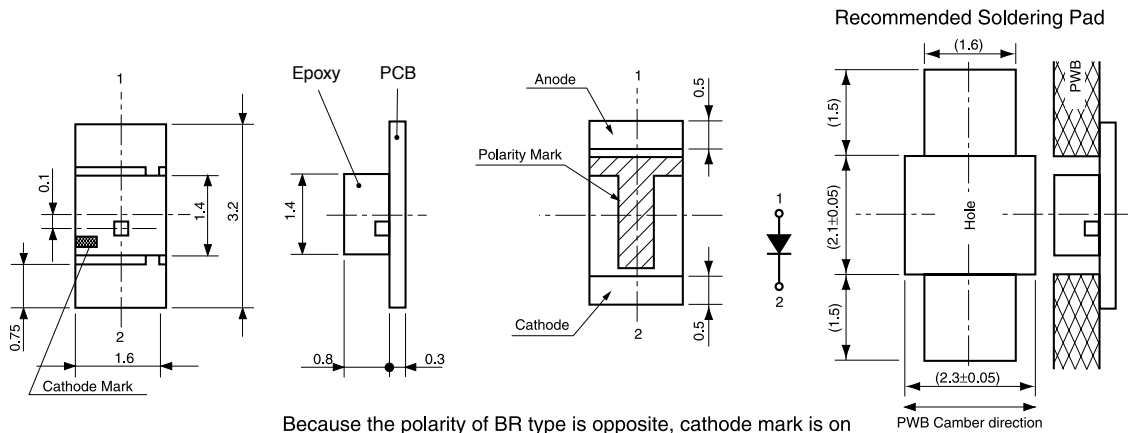
Features

- Designed to be mounted on one side of the PCB with light emitting through a hole.
- Eliminates the need for second reflow soldering
- Excellent for status indicator and edge lighting

Applications

- Mobile Devices (cellular phones, pagers, PDAs)
- Computers
- Telecommunication

Outline Dimensions



Unit: mm
Tolerances ± 0.1

Electro-Optical Characteristics

(Ta=25°C)

Type No.	Material	Emitted Color	Lens Color	Luminous Intensity I _V			Wavelength Spectral Line Half Width				Forward Voltage V _F			Reverse Current I _R		Viewing Angle (2 θ 1/2)
				MIN.	TYP.	I _F	Peak λ _p TYP.	Dominant λ _d TYP.	Δλ TYP.	I _F	TYP	MAX.	I _F	MAX.	V _R	
BR1111R	GaAlAs	Red	Milky White	7.6	12.7	20	660	647	30	20	1.7	2.3	20	100	4	140°
AA1111R	GaAsP	Orange		2.2	3.7	20	605	606	30	20	2.2	2.8	20	100	4	150°
AY1111R	GaAsP	Yellow		2.2	3.7	20	580	590	30	20	2.2	2.8	20	100	4	
PY1111R	GaP	Yellow Green		7.6	12.7	20	570	572	30	20	2.1	2.8	20	100	4	
PG1111R	GaP	Green		4.1	6.9	20	560	567	30	20	2.1	2.8	20	100	4	
BG1111R	GaP	Pure Green		1.6	2.7	20	555	558	30	20	2.1	2.8	20	100	4	
Units				mcd		mA	nm			mA	V		mA	μA	V	Deg.

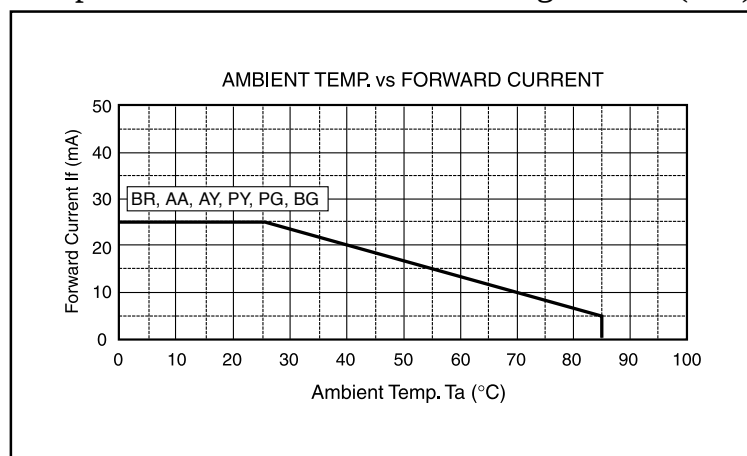
Absolute Maximum Ratings

(Ta=25°C)

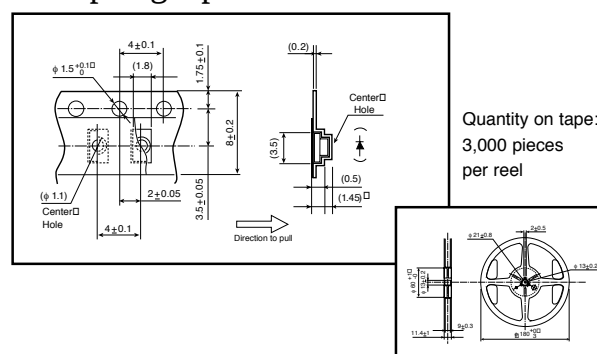
Item	Symbol	Red	Orange	Yellow	Yellow Green	Green	Pure Green	Units
		BR	AA	AY	PY	PG	BG	
Power Dissipation	Pd	57.5	70	70	70	70	70	mW
Forward Current	I _F	25	25	25	25	25	25	mA
Peak Forward Current	I _{FM}	60	60	60	60	60	60	mA
Reverse Voltage	V _R	4	4	4	4	4	4	V
Operating Temperature	Topr	-30 to +85						°C
Storage Temperature	Tstg	-40 to +100						°C
Derating*	ΔI _F	0.36 (DC) 0.86 (Pulse)						mA/°C

* Ta=25°C, I_{FM} applies for the pulse width ≤ 1msec. and duty cycle ≤ 1/20.

Operation Current Derating Chart (DC)



Taping Specifications

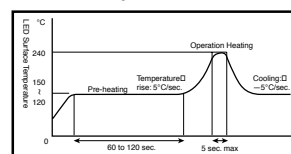


Precautions

Please follow these handling precautions to prevent damage to the chip and ensure its reliability.

1. Soldering conditions:

- Soldering iron:** Temperature at tip of iron: 280°C max. (30W max.)
Soldering time: 3 sec. max.
- Dip soldering:** Preheating: 120 ~ 150°C max. (resin surface temp.)
60 ~ 120 sec. max. Bath temperature: 260°C max. Dipping Time: 5 sec. max.
- Reflow Soldering:**

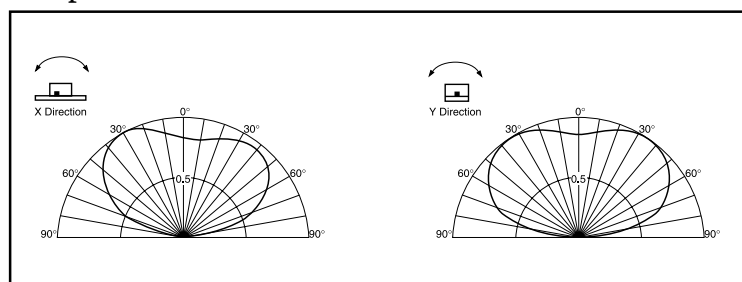


2. Cleaning:

- If cleaning is required, use the following solutions for less than 1 minute, at less than 40°C.
- Appropriate chemicals: Ethyl alcohol and isopropyl alcohol.
- Effect of ultrasonic cleaning on the LED resin body differs depending on such factors as the oscillator output, size of PCB and LED mounting method. The use of ultrasonic cleaning should be enforced at proper output after confirming there is no problem.

Product specifications subject to change without notice. PG1111R-0301

Spatial Distribution



Stanley Electric Sales of America, Inc.

2660 Barranca Parkway, Irvine, CA 92606 • Tel: 800-LED-LCD1 (533-5231) • Fax: 949-222-0555
Website: www.stanley-electric.com

STANLEY